

**REMARKS/ARGUMENTS**

The Office Action mailed May 31, 2007, has been received and reviewed. Claims 1, 2 and 4 through 14 are currently pending in the application. Claims 1 and 9 stand rejected. Claims 2, 4 through 8 and 10 through 14 have been objected to as being dependent upon rejected base claims, but the indication of allowable subject matter in such claims is noted with appreciation. Applicant has respectfully request reconsideration of the application in light of the remarks below.

**Double Patenting Rejection Based on U.S. Patent No. 6,975,035**

Claims 1 through 9 stand rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 41 and 51 of U.S. Patent No. 6,975,035.

Applicant respectfully traverses this rejection, as hereinafter set forth. Specifically, Applicant respectfully asserts that neither claim 1 or claim 9 of the present application is patentably indistinct from claims 41 and 51 of U.S. Patent No. 6,975,035. Applicant notes that claims 41 and 51 each depend directly from independent claim 39 of the '035 patent and, thus, incorporate all of the limitations thereof. Thus, since claim 39 was not asserted as being patentably indistinct from either claim 1 or claim 9, the obviousness-type double patenting rejection is improper.

Further, claim 1 of the present application recites a method of fabricating an interposer substrate, while claim 39 of the '035 patent recites a method of assembling a flip chip semiconductor device assembly, two distinctly different methods. Claim 39 requires mounting an interposer substrate to a semiconductor die, and further requires that the plurality of recesses in the interposer substrate be *“sized so that a gap is left adjacent a portion of at least some of the conductive bumps [of the semiconductor die] in at least some of the recesses, the at least one opening formed in the interposer substrate extending to the gaps adjacent the at least some conductive bumps in the at least some recesses”* and further recites *“introducing a dielectric filler material in flowable form into the at least one opening in sufficient quantity to extend to at least some of the gaps.”* The italicized language, or its equivalent, is nowhere to be found in claim 1 or claim 9 of the present application and it is not seen how either claims 1 or 9 of the present

application would be obvious in light of the combination of either claims 39 and 41 or claims 39 and 51.

Accordingly, the Examiner is respectfully requested to withdraw this rejection, as being in error, or to further explain the rationale for asserting same.

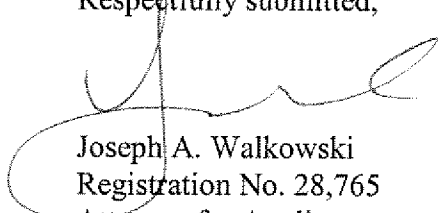
**Objections to Claims 2, 4 through 8 and 10 through 14/Allowable Subject Matter**

Claims 2, 4 through 8 and 10 through 14 stand objected to as being dependent upon rejected base claims, but are indicated to contain allowable subject matter and would be allowable if placed in appropriate independent form. Applicant appreciates this indication of allowable subject matter, but respectfully asserts that claims 2, 4 through 8 and 10 through 14 are allowable in their present form.

**CONCLUSION**

Claims 1, 2 and 4 through 14 are believed to be in condition for allowance, and an early notice thereof is respectfully solicited. Should the Examiner determine that additional issues remain which might be resolved by a telephone conference, the Examiner is respectfully invited to contact Applicant's undersigned attorney.

Respectfully submitted,



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